**A539-DM**

Dual cure epoxy adhesive: UV-Heat cure adhesive

**PRODUCT DESCRIPTION:**
- Base chemistry: epoxy only, cationic polymerization
- One component adhesive ready for use, solvent-free, UV and/or heat curing

**PRODUCT USE:**
- Active alignment of components for optoelectronics and semiconductor packaging
- Bonding of opaque substrates and optical parts

**FEATURES:**
- Epoxy only, high adhesion, high Tg, long shelf and working life, room temperature stable, not sensitive to oxygen in cure process, excellent reliability performances, robust for solder reflow process

**INSTRUCTIONS FOR USE:**
1) Clean the substrates to remove contamination, dust, moisture, salt and/or oil
2) Dispense adhesive on substrates
3) Bond substrates (with active alignment – optional)
4) UV cure to fix alignment or to bond
5) Thermal cure: to cure adhesive in shadow area and to improve adhesion of bonded parts

**GENERAL USAGE INFORMATION:**

**Shipment:** adhesive is shipped in cold pack

**Storage:** After receipt, cold storage at 3 to 5 °C, or -20 °C to -40 °C in the original container is required

**Before use:** The cold adhesive needs to reach RT (23-25°C) before use. The container needs to sit at RT, adding heat is not allowed. Room temperature equilibration time is dependent on container size, but a 3-30 gram syringe equilibration time is approximately 30-60 minutes. Condensed water on the container must be removed prior to use

**Shelf life (-40 to -20°C)/(3 to 5°C):** 6 months/4months

**Pot life or working life (20 - 25°C):** 1 week

**SAFETY AND HANDLING**

The uncured adhesive can be cleaned from apparatus with isopropyl alcohol (IPA), methyl ethyl ketone (MEK), or commercial alcohol based cleaning solution. Avoid direct skin and eye contact. Use only in well ventilated areas. Use protective clothing, gloves and safety goggles. Read Material Safety Data Sheet before handling.

**CURING CONDITIONS:** 3 curing ways: UV + heat or heat or UV

1) **UV + Heat curing:** both UV and heat are used in the curing process

   **First step:** UV cure
   - Metal halide/Mercury UV: UV-A (320-400 nm), intensity: 100-1,000 mW/cm²
   - LED-365 nm, UV light intensity: 100 to 1,000 mW/cm²

   **LED-365 nm**
<table>
<thead>
<tr>
<th>UV intensity(mW/cm²) x time (sec)</th>
<th>Metal Halide/Mercury(UV-A: 320-400 nm)</th>
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<tbody>
<tr>
<td>100</td>
<td>100</td>
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<tr>
<td>or 200</td>
<td>50 sec or more</td>
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   **Second step:** heat cure: the adhesive is exposed to UV light first, then heat cure
   - * 80 to 85 °C for 30 to 60 minutes if the adhesive sees some UV light. If adhesive sees no UV light, heat cure is at 100°C for 1-2 hrs

2) **Heat curing:** heat is the only source for curing, the adhesive see no UV light

   **First step:** UV cure
   - 100°C for 1-2 hrs or 125°C for 1 hr or 150°C for 1 hr
   - The heat time of the components must be added to the total cure time of the adhesive for the process

3) **UV Curing:** UV is the only source of curing

   **First step:** UV cure
   - 1000 mW/cm² x 5 to 10 sec metal halide/mercury light source with UV-A (320-400 nm)
   - or with LED-365 nm
   - If the substrate absorbs curing light, then the actual cure time needs to be increased.
   - The effect of humidity is greater for very thin film, if the adhesive layer is <10 µm, then the adhesive needs to be between two substrates or curing in nitrogen is required.
   - To ensure good curing speed, the humidity should be <60% RH
   - Epoxy adhesives have post cure properties. Adhesion strength should be conducted at least 24 hrs after part assembly.

The maximum adhesion strength is achieved by HEAT cure. For best adhesion, UV fix cure should be kept at a minimum and the majority of the bonded components should be cured by HEAT

**TYPICAL PROPERTIES**

**Uncured resin**

- Viscosity at 25 °C, mPa.s or cps: 1,900 to 2,200
- Density (g/mL): 1.1

**Cured film**

- Outgas, weight % (per Telcordia GR-1221): 0.01
- Outgas, weight % (per MIL-STD 883/5011): 0.03
- Water permeability (g/m 24 hrs, 50 °C/95% RH, 75 µm film): 3 x 10⁻⁴
- Shrinkage (linear, %): < 0.3
- Hardness -- Shore D: 90
- Glass transition temperature (DMA, °C): 145
- Refractive index of cured film (25°C): 1.57
- @ 589 nm
- @ 1310 nm: 1.56
- @ 1550 nm: 1.55
- Coefficient of thermal expansion (DMA)
  - below Tg (x10⁶), °C⁻¹: 25
  - above Tg (x10⁶), °C⁻¹: 64
- Physical properties tested at 25°C, 50% RH (ASTM D638)
  - Tensile strength, MPA: 480
  - Elongation (%): 20
  - Young’s Modulus, MPA: 2,300
  - Operating temperature, °C: -40 to 180
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A539DM 20 micron film between glass slides

Note: Air reference; no correction for surface reflection

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A539-DM
20 μm thickness between glass substrates